

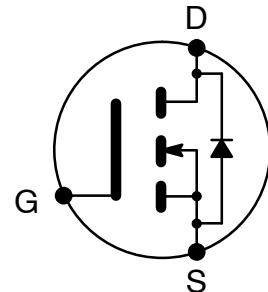


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**NTE2924
MOSFET
N-Ch, Enhancement Mode
High Speed Switch
TO247 Type Package**

Features:

- Dynamic dv/dt Rating
- Repetitive Avalanche Rated
- Isolated Central Mounting Hole
- Fast Switching
- Ease of Parallelizing
- Simple Drive Requirements



Absolute Maximum Ratings:

Continuous Drain Current ($V_{GS} = 10V$), I_D	
$T_C = +25^\circ C$	6.8A
$T_C = +100^\circ C$	4.3A
Pulsed Drain Current (Note 1), I_{DM}	27A
Power Dissipation ($T_C = +25^\circ C$), P_D	150W
Derate Linearly Above $25^\circ C$	1.2W/ $^\circ C$
Gate-to-Source Voltage, V_{GS}	± 20
Single Pulse Avalanche Energy (Note 2), E_{AS}	410mJ
Avalanche Current (Note 1), I_{AR}	6.8A
Repetitive Avalanche Energy (Note 1), E_{AR}	15mJ
Peak Diode Recovery dv/dt (Note 3), dv/dt	3V/ns
Operating Junction Temperature Range, T_J	-55° to +150° $^\circ C$
Storage Temperature Range, T_{stg}	-55° to +150° $^\circ C$
Lead Temperature (During Soldering, 1.6mm from case for 10sec), T_L	+300° $^\circ C$
Mounting Torque (6-32 or M3 Screw)	10 lbf•in (1.1N•m)
Thermal Resistance, Junction-to-Case, R_{thJC}	0.83° $^\circ C/W$
Thermal Resistance, Junction-to-Ambient, R_{thJA}	40° $^\circ C/W$
Typical Thermal Resistance, Case-to-Sink (Flat, Greased Surface), R_{thCS}	0.24° $^\circ C/W$

Note 1. Repetitive rating; pulse width limited by maximum junction temperature.

Note 2. $V_{DD} = 50V$, starting $T_J = +25^\circ C$, $L = 16mH$, $R_G = 25\pm$, $I_{AS} = 6.8A$

Note 3. $I_{SD} \leq 6.8A$, $di/dt \leq 80A/\mu s$, $V_{DD} \leq 600V$, $T_J \leq +150^\circ C$

Note 4. Pules Width \leq 300s, Duty Cycle \leq 2%.

Electrical Characteristics: ($T_J = +25^\circ\text{C}$ unless otherwise specified)

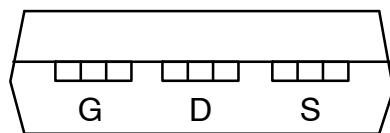
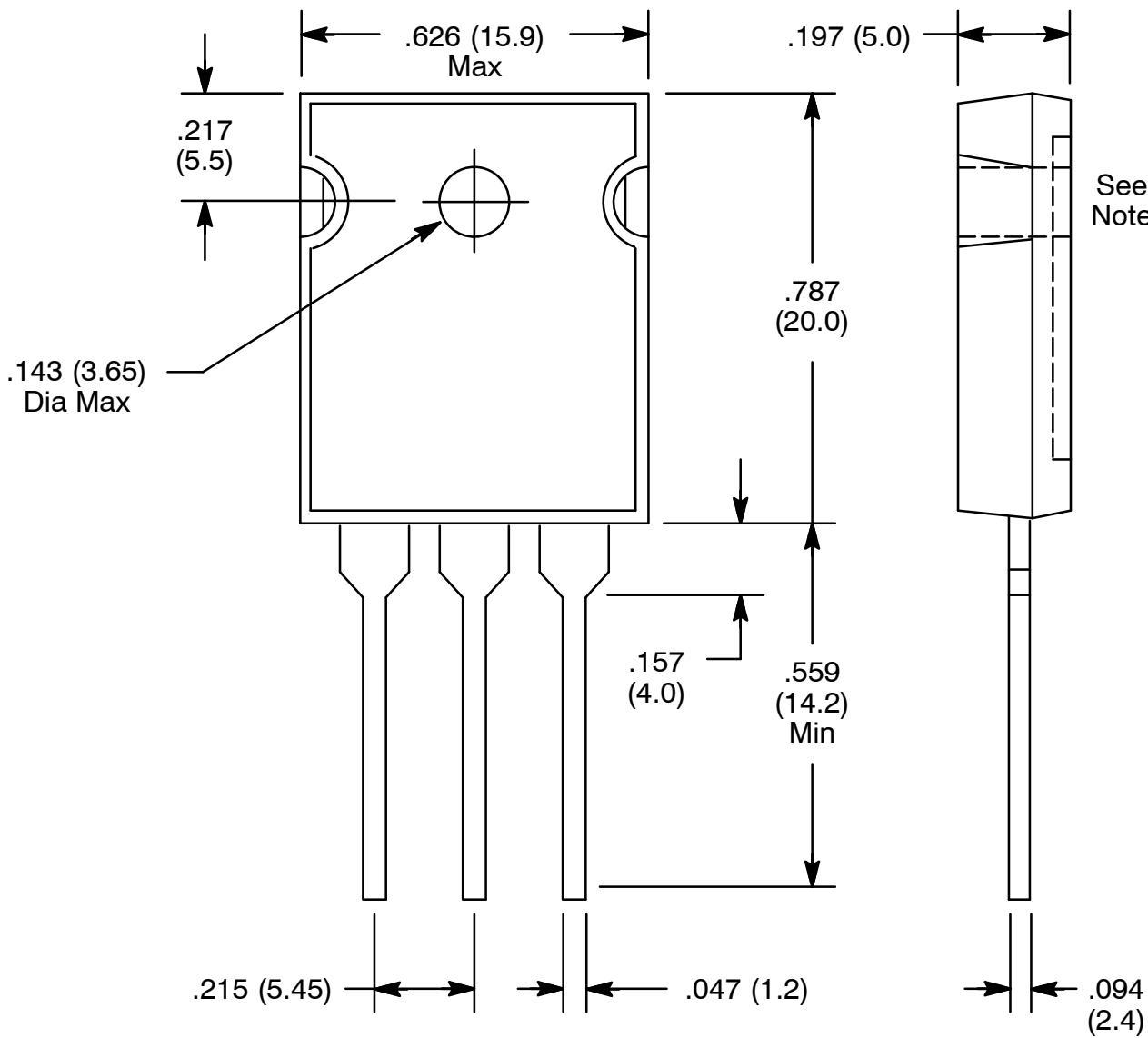
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\text{mA}$	600	-	-	V
Breakdown Voltage Temp. Coefficient	$\frac{V_{(\text{BR})\text{DSS}}}{T_J}$	Reference to $+25^\circ\text{C}$, $I_D = 1\text{mA}$	-	0.70	-	$\text{V}/^\circ\text{C}$
Static Drain-to-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 4.1\text{A}$, Note 4	-	-	1.2	\pm
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\text{mA}$	2.0	-	4.0	V
Forward Transconductance	g_{fs}	$V_{\text{DS}} = 100\text{V}, I_D = 4.1\text{A}$, Note 4	4.9	-	-	mhos
Drain-to-Source Leakage Current	I_{DSS}	$V_{\text{DS}} = 600\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	100	mA
		$V_{\text{DS}} = 480\text{V}, V_{\text{GS}} = 0\text{V}, T_J = +125^\circ\text{C}$	-	-	500	mA
Gate-to-Source Forward Leakage	I_{GSS}	$V_{\text{GS}} = 20\text{V}$	-	-	100	nA
Gate-to-Source Reverse Leakage	I_{GSS}	$V_{\text{GS}} = -20\text{V}$	-	-	-100	nA
Total Gate Charge	Q_g	$I_D = 6.2\text{A}, V_{\text{DS}} = 360\text{V}, V_{\text{GS}} = 10\text{V}$, Note 4	-	-	60	nC
Gate-to-Source Charge	Q_{gs}		-	-	8.3	nC
Gate-to-Drain ("Miller") Charge	Q_{gd}		-	-	30	nC
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 300\text{V}, I_D = 6.2\text{A}, R_G = 9.1\pm$, $R_D = 47\pm$, Note 4	-	13	-	ns
Rise Time	t_r		-	18	-	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	55	-	ns
Fall Time	t_f		-	20	-	ns
Internal Drain Inductance	L_D	Between lead, .250in. (6.0) mm from package and center of die contact	-	5.0	-	nH
Internal Source Inductance	L_S		-	13	-	nH
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1\text{MHz}$	-	1300	-	pF
Output Capacitance	C_{oss}		-	160	-	pF
Reverse Transfer Capacitance	C_{rss}		-	30	-	pF

Source-Drain Ratings and Characteristics:

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Continuous Source Current (Body Diode)	I_S		-	-	6.8	A
Pulsed Source Current (Body Diode)	I_{SM}	Note 1	-	-	27	A
Diode Forward Voltage	V_{SD}	$T_J = +25^\circ\text{C}, I_S = 6.8\text{A}, V_{\text{GS}} = 0\text{V}$, Note 4	-	-	1.5	V
Reverse Recovery Time	t_{rr}	$T_J = +25^\circ\text{C}, I_F = 6.2\text{A}$, $dI/dt = 100\text{A}/\mu\text{s}$, Note 4	-	450	940	ns
Reverse Recovery Charge	Q_{rr}		-	3.8	7.9	μC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

Note 1. Repetitive rating; pulse width limited by maximum junction temperature.

Note 4. Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.



TO247

Note: Drain connected to metal part of mounting surface.